

MLA150 Operation

| | |
|---|-----------|
| Overview | 1 |
| Restrictions & Precautions | 1 |
| Operation | 1 |
| <i>CAD file Design Info</i> | 1 |
| <i>Transfer your design file(s) to the tool via Nanofiles FTP</i> | 2 |
| Setting up the exposure job | 3 |
| <i>Standard Exposure (without Overlay)*</i> | 4 |
| <i>Standard Exposure with Overlay</i> | 8 |
| <i>Substrate Loading</i> | 15 |
| If Loading a Full Wafer (round) | 16 |
| If Loading a Piece (irregular or rectangular) | 17 |
| <i>Substrate Unload</i> | 18 |
| <i>Re-align the Substrate Rotation</i> | 19 |
| Design Conversion | 20 |

Overview

This SOP gives instructions on how to setup and execute an exposure job with the MLA150. Follow the instructions carefully. If you require more detailed information, refer to the related document User Guide.

Restrictions & Precautions

Max Substrate Thickness: 9mm
Max. Substrate Size: 9x9-inches
Minimum Substrate Size: 5x5 mm

Operation

The user and password for the Windows PC is written at the tool. If you ever have to restart the computer, make sure to wait ~1min after login before launching MLA150Menu.exe, as it loads background drivers.

CAD file Design Info

- GDS / GDSii is the preferred file format (fewest errors). DXF, CIF, BMP and Gerber are also available.

MLA150 Operation

- Note the Cell that you want to print. Only one Cell may be printed, so use Cell Instancing to create combinations of Cells.
- Note the Layer(s) to print. The system can select either a single Layer, or can combine multiple layers via Boolean OR.
- The Origin (0,0) in your file is the reference for all coordinates during exposure, including alignment mark exposure/measurement.
- Your file name cannot contain any spaces or special characters except for underscores.
- Make sure the file extension is all lower case (e.g. .gds not .GDS) as some design programs (e.g. Klayout) will create a file with an upper case file extension.

Transfer your design file(s) to the tool via Nanofiles FTP

- You must have a folder named according to your group/company on the machine for ~24hrs in order for the MLA150 folder to appear on the Nanofiles SFTP.

On your own computer:

1. Log into the Nanofiles SFTP folder with an FTP client.
See the [Wiki FAQ for steps to get a Nanofiles FTP login](#).
2. Upload your design files into the “**MLA150_Heidelberg**” folder.
You can read/write and create subfolders in this directory.

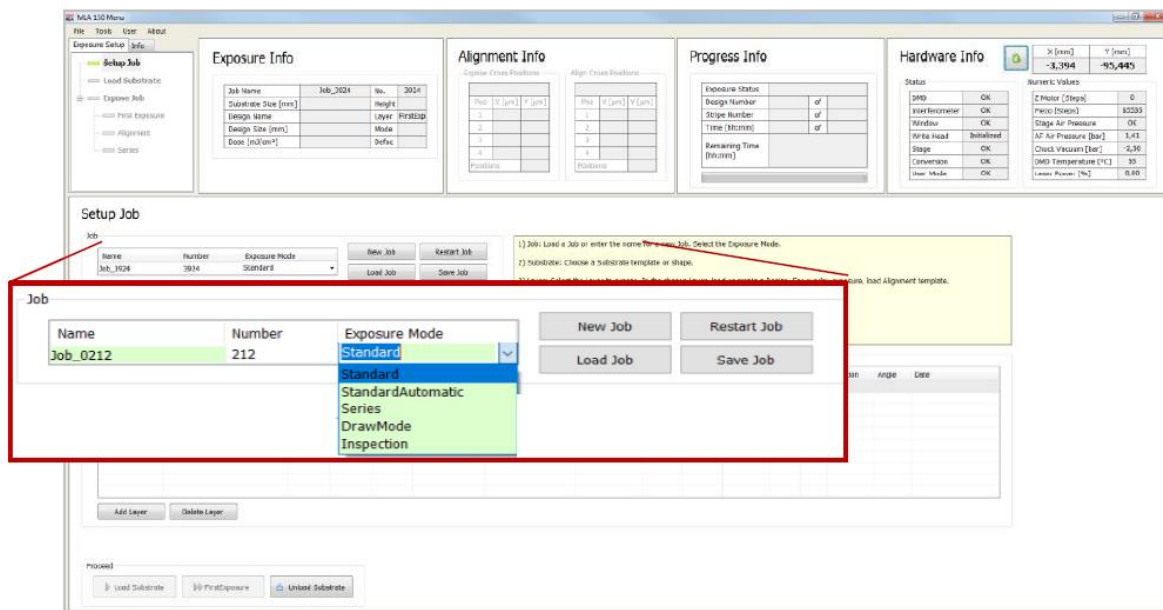
On the MLA computer:

3. Run the “**Sync to Nanofiles**” script on the Desktop, Start Menu or Task Bar.
 - a. Make sure there aren't any errors in the log window, then press any key to complete.
4. Open the “**Users_Nanofiles**” folder (Desktop, Start Menu or File Explorer).
5. Copy or Cut the new design files.
6. Open the “**Designs**” folder, and navigate into the correct subfolder for your file type.
7. Paste the CAD file into the correct sub folder.
 - a. Do NOT make subfolders within these directories, or alter the folder names, or the *Convert* software will not be able to read your files.

Setting up the exposure job

If the 'MLA 150 Menu' software is not open, click the shortcut icon on the desktop of the User PC, the wizard opens and leads you to the **Setup Job** panel, where a new job has been created automatically. This system will generate a **Name** and a **Number**. Change the name by clicking into the **Name** field.

The naming convention is *LastnameFirstinitial_jobname* or *companyname_jobname* (e.g. *sawyerl_myfirstjob* or *staff_trainingjob_oct10*).



From the drop-down list, select one of the available exposure modes:

- **Standard:** To expose a single design for each layer. Overlay exposures are possible in this mode.
- **Series:** To expose designs (e.g. dose test) several times at different positions with varying parameters (dose or/and defoc). It can also be used for finding the appropriate dose and defoc relation for the exposure.
- **Draw Mode:** To create boxes, circles or ellipses of arbitrary size limited only by the camera field. Used for creating alignment marks/connections on arbitrary structures or for repairing imperfections in structures of an exposed layer. For more information, see pg.60 of the User Manual available at the tool.
- **Inspection:** To inspect and measure the exposed structures.

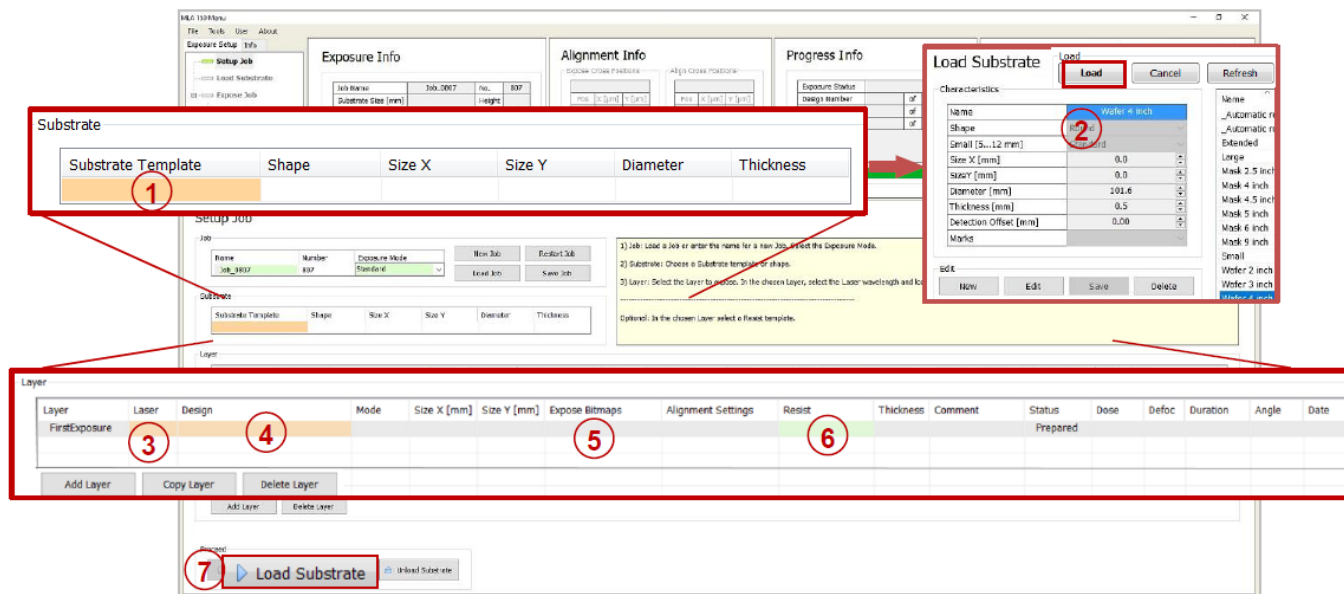
If you do not intend to use the new job, you can also choose from the following options in the Job frame:

- To continue or repeat a job, click **Load Job**. A list appears from where you select the required job. There is a **Search** option available as well.
- To repeat an exposed layer of that job you need to copy the job with **Restart Job**. The system deletes the process data of the selected job and sets up the job with the same settings but with a new job name/number.

MLA150 Operation

- To start another new job after you have finished an exposure job, click **New Job**. The new job has a new number and a new, but editable, name. Continue with the instructions for a new job.

Standard Exposure (without Overlay)*



*For overlay exposures go to the **Standard Exposure with Overlay** section in this SOP.

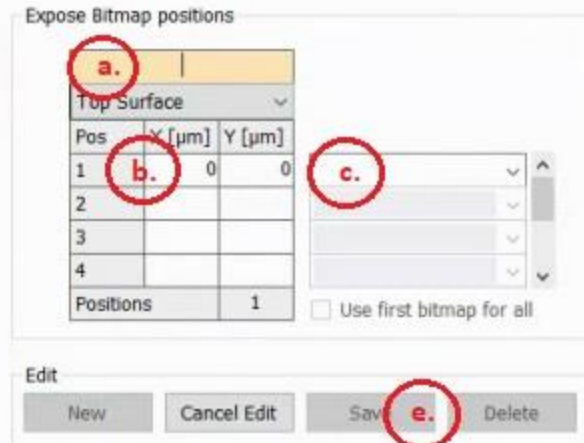
In the **Substrate** frame:

- Double-click **Substrate Template**.
- For whole wafers select **_Automatic round_OAF**
For pieces <9mm select **_Automatic rectangular_Sml_OAF**
For pieces >9mm select **_Automatic rectangular_Std_OAF**
Then click **Load**.

In the **Layer** frame:

- Select a laser from the **Laser** dropdown list, the choices are 375 or 405 nm.
 - The laser wavelength corresponds to the photoresist you are exposing.
- Double-click **Design** and load the design file.
For instructions on how to convert a new design, refer to the **Design Conversion** section at the end of this SOP.
- To expose alignment marks in addition to your design, you can load or create a template for alignment crosses or shapes which are exposed on the layer. To load a template, double-click into the value field titled **Expose Bitmaps**, select a bitmap template file from the list, and click **Load** (or just double click the file). To create a new file:

Load Exposure Bitmaps

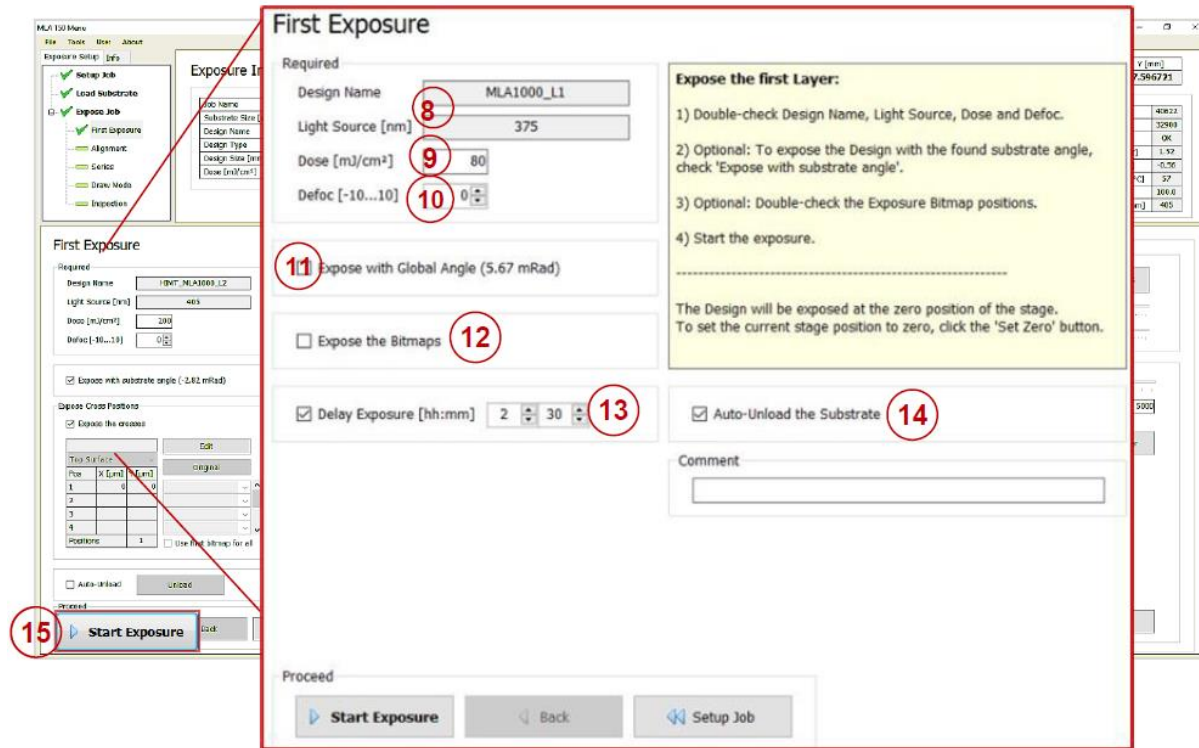


- a. In the **Edit** frame, select **New**. A cursor will appear in the field for the file name. Give the file a name using the standard naming convention, eg. *sawyerl_alignmentOct10*.
 - b. **Pos 1** in the table will be populated with 0,0 by default. If you wish to change this, select a cell and enter a coordinate value.
 - i. Make sure at least one or two of your alignment marks are at coordinates $Y \leq 0$, to allow the Wide-view Overview camera to see them.
 - c. After you have the correct coordinates inputted for **Pos 1**, use the drop down menu next to the coordinate entries to select a bitmap design. Standard bitmaps are “Cross” and “cross_inverted”. You can also select **<other>** from the drop down menu and a pop-up window will appear with previews of the bitmap files.
 - d. Repeat the previous two steps for additional bitmap positions (up to 8).

NOTE: After entering coordinates for **Pos 2**, the **Use first bitmap for all** option will become available. Selecting this will automatically populate the bitmap design used in **Pos 1** for all subsequent positions.
 - e. When you are finished entering bitmap positions, select **Save**. Your new bitmap template file will appear highlighted in the file list.
 - f. Either select **Load** or double click the file to add it to the job.
6. Optionally, double-click value field titled **Resist** to load a resist profile. This will populate the fields for **Dose** and **Defoc** when you get to the **First Exposure** panel. Select a resist file from the list, and click **Load** (or just double click the file).
 7. Load your Substrate with **[Load Substrate]** → See the “**Substrate Loading**” section of the procedure, on page 15.

MLA150 Operation

In the **First Exposure** panel:



8. Double-check the **Design Name** and the **Light Source**.
9. Double-check or edit **Dose** value by entering the value into the text field.
10. Double-check or edit **Defoc** by selecting the value with the spin buttons (range is -25 to 25).
11. Activate the **Expose with Global Angle** checkbox if it is not already selected.

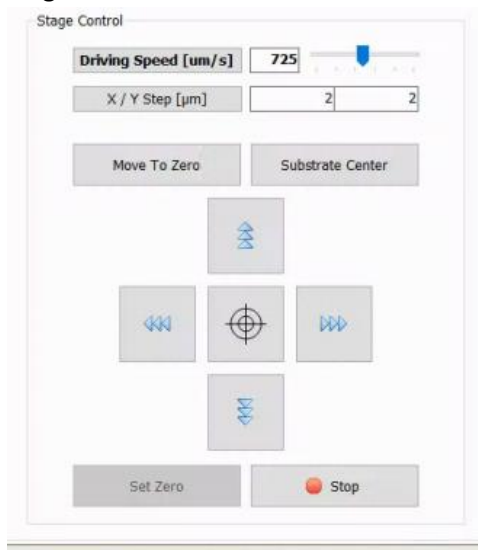
IMPORTANT: If you are going to expose additional layers on your substrate or if flat/edge alignment is critical, the angle reading in parentheses needs to be <10 mRad (0.6°).

If measured substrate angle is >10 mRad:

- a. Click **Setup Job** at the bottom of the screen to return to the **Setup Job** panel.
 - b. Click **Unload Substrate**, a pop-up window will appear confirming you want to unload, click **OK**.
 - c. Wait for the unload sequence to complete. A pop-up window will appear indicating the substrate has been unloaded, click **OK**.
 - d. Open the sash, release the chuck vacuum, and reposition your substrate using the corresponding alignment fixture.
 - e. Engage the chuck vacuum, remove the alignment fixture, and close the sash.
 - f. Return to Step 7.
12. If you loaded an **Expose Bitmaps** file in the **Setup Job** panel, verify **Expose the Bitmaps** checkbox is selected and that the settings are correct. You can also view the graphic in the **Substrate** frame which shows the approximate location of the bitmaps as numbered crosshairs.
- IMPORTANT:** Although it gives you the option to *create* a bitmap template file on this screen, **DO NOT** do this as it will cause an error.
13. If desired, activate Auto-Unload. The system executes the unloading procedure automatically.

MLA150 Operation

- a. Do *not* use the “Delay Exposure” option.
14. Type in the **Dose** and **Defocus** values for your exposure. These will be pre-filled from the Resist template chosen.
15. By default, the system will expose the design with the CAD file’s (0,0) origin at the substrate center. To move the exposure location, use the controls in the **Stage Control** frame to drive the stage.



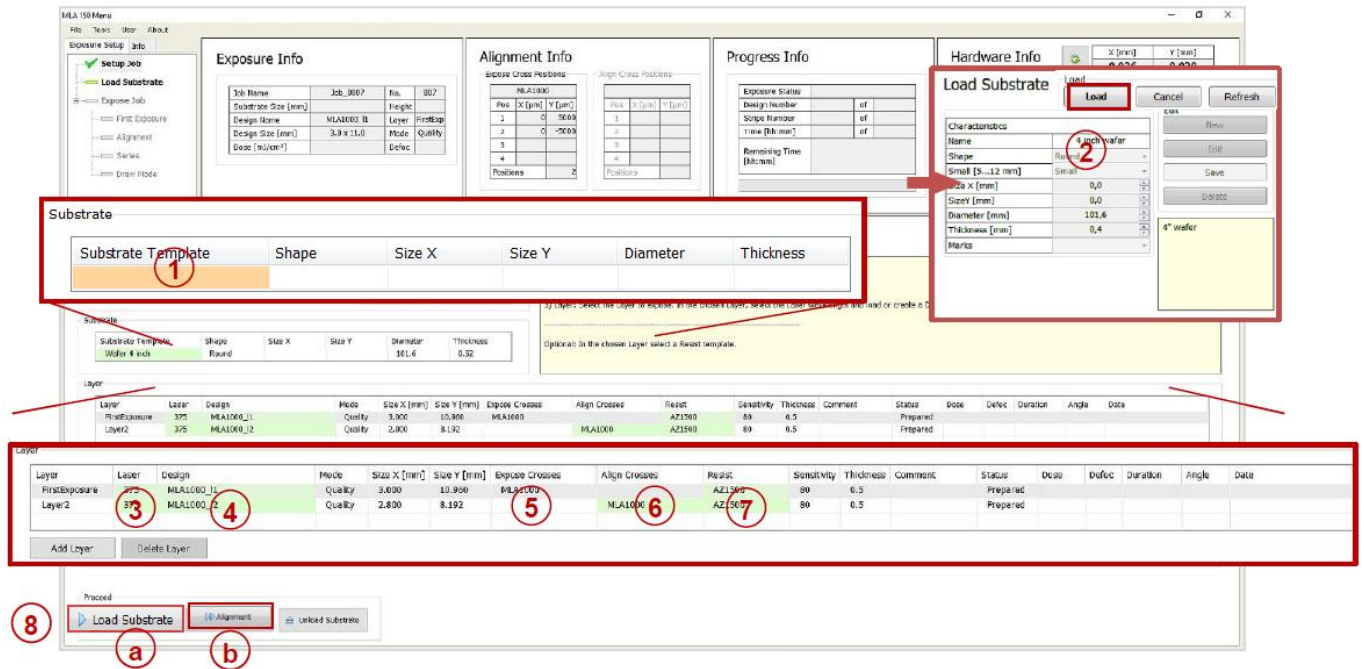
- You can switch between **Driving Speed** (continuous movement) and **X/Y Step** (stepwise movement). In **Driving Speed** mode, change the driving speed [$\mu\text{m/s}$] either by using the slider or by clicking into the field and entering the speed manually. Alternatively, you can click into the slider field to use the arrow keys on the keyboard for setting the speed. In **X/Y Step** mode enter the step size [μm] for the X and Y direction into the corresponding fields.
- The **Arrow** buttons are used to drive the stage.
- Alternatively, the **Target** button in the center of the **Arrow** buttons can be used to drive the stage to a specific location by clicking on the camera screen. When you click this button it is good for one movement, you will need to click it again for subsequent movements. When activated, use the mouse to move the cursor that has appeared on the camera display to the position you want to move to and then left click on the mouse to execute.
Use the **S** and **C** keyboard keys to toggle the display of a square/circle on the crosshair, and the **Mouse-Wheel** to increase/decrease the size of the guides.
- Additionally, there are **Focus** and **Brightness** controls in the **Camera Control** frame, you can manipulate these the same ways as with **Driving Speed**.
- Substrate Center moves to the detected substrate center
- Set Zero will set the currently centered location to coordinate (0,0), such that the CAD file’s origin (0,0) will be exposed at this location
- Move To Zero moves back to the (0,0) coords, which defaults to the detected substrate center.
- Stop immediately halts a stage movement.

16.

17. Click **Start Exposure**.

Standard Exposure with Overlay

In the **Substrate** frame:

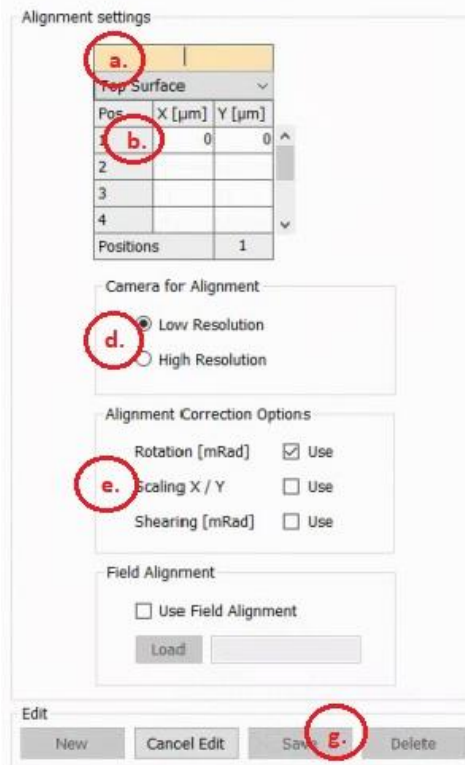


For alignment, at least the second layer must be chosen. The first row in the list is always reserved for the first exposure without overlay. To leave out the first exposure row, leave it blank and click **Add Layer**.

For alignment, make sure the layer “**Layer2**” is selected/highlighted. The “*FirstExposure*” layer can be blank.

1. Select a laser from the **Laser** dropdown list, the choices are 375 or 405 nm.
 - a. The laser wavelength corresponds to the photoresist you are exposing.
2. Double-click **Design** and select the design for your overlay exposure. For instructions on how to convert a new design, refer to the **Design Conversion** section at the end of this SOP.
3. You can load or create a template for alignment crosses or shapes which are exposed on the layer. See Step 5 of the **Standard Exposure (without Overlay)** section of this SOP for detailed instructions.
4. Double-click the value field titled **Alignment Settings**. From there select an alignment settings template file from the list, choose the “_Manual” setting and click **Load** (or just double click the file). Optionally choose a previous template, or to create a new one:

Load Alignment Settings



- a. In the **Edit** frame, select **New**. A cursor will appear in the field for the file name. Give the file a name using the standard naming convention.
- b. **Pos 1** in the table will be populated with 0,0 by default. If you wish to change this, select a cell and enter a coordinate value.
NOTE: Whenever possible, your First alignment position should always be on the bottom half (-Y) of the substrate or at 0,0. This will to allow the **Overview** camera to be used if needed.
- c. Repeat the previous two steps for additional alignment positions (up to 8).
- d. In the **Camera for Alignment** frame, select either **Low Resolution** or **High Resolution**.

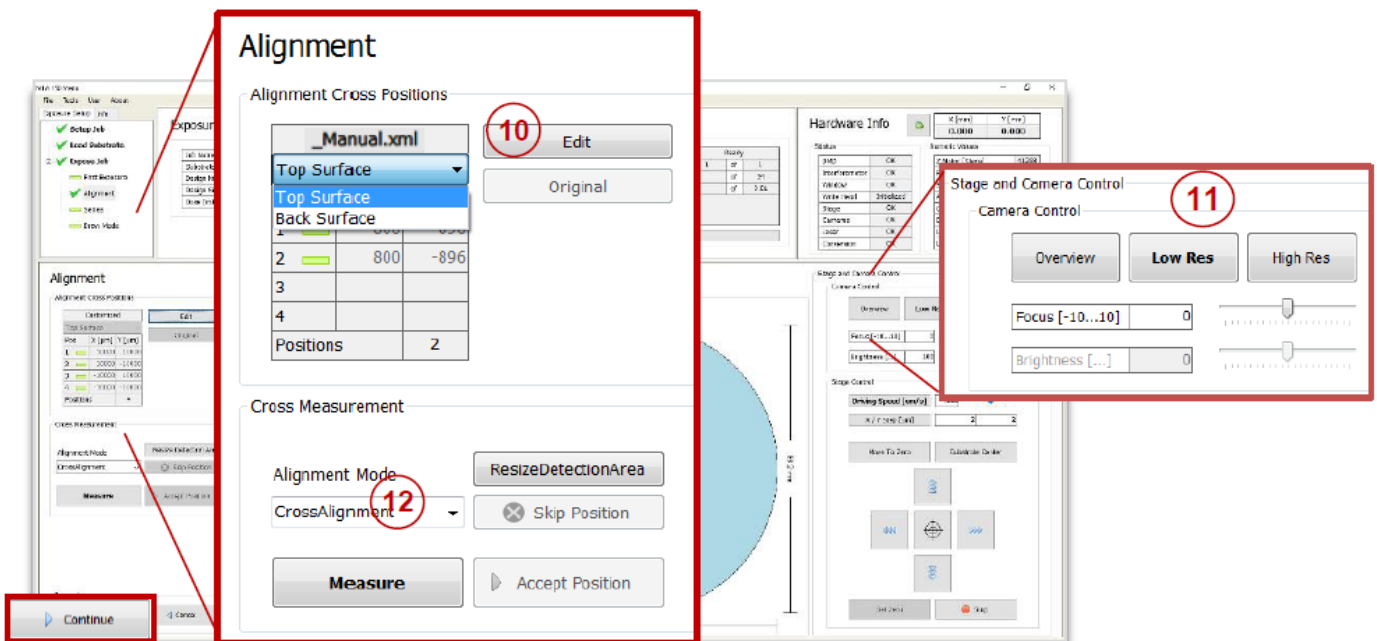
| | Field of view |
|-----------------|---------------------------------------|
| High Res | 190 μm x 140 μm |
| Low Res | 640 μm x 480 μm |

- NOTE:** This will be the initial camera used when you begin your alignment, you will be able to select the other cameras during the alignment process. For more accurate alignment, it is recommended to use the High Res camera.
- e. In the Alignment Correction Options frame make sure the **Rotation** option is selected. **Scaling X/Y** and **Shearing** are also available options.
 - a. These will adjust your CAD file to accommodate measured Rotation, Scaling and Non-Orthogonality measured in the alignment mark positions.
 - f. The **Field Alignment** feature is not covered by this SOP.
- NOTE:** When you get to the **Alignment: Exposure** panel, you will have the ability to select/deselect these options as well.

MLA150 Operation

- g. When you are finished, select **Save**. Your new alignment positions template file will appear highlighted in the file list.
 - h. Either select **Load** or double click the file to add it to the job.
- Recommended: To set the alignment marks manually, select the template **_Manual** for manual setup. When using this template file, you will enter the alignment positions after wafer loading sequence.
5. Optionally, double-click value field titled **Resist** to load a resist profile. This will populate the fields for **Dose** and **Defoc** when you get to the **Alignment Exposure** panel. Select a resist file from the list, and click **Load** (or just double click the file).
 6. Load your Substrate with [**Load Substrate**] → See the “**Substrate Loading**” section of the procedure, on page 15.
 7. Click **Alignment >>**.

In the **Alignment** panel:



8. Not used.

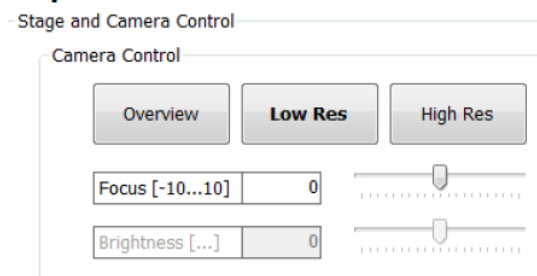
In the **Alignment Settings** frame:

9. Type In or Double-check the positions of the alignment marks taken from the template file. You can also view the graphic in the **Substrate** frame which shows the approximate location of the alignment locations as numbered crosshairs.
 - To change the cross positions, click **Edit**. Now the table entries can be edited and the button caption changes to **Apply**. Enter new values and click **Apply** to leave the editing mode. The positions are stored in a temporary file and turned into a permanent template after exposure start.
 - To restore the original positions from the file, click **Original**.

MLA150 Operation

- If the template **_Manual** was selected, set the alignment marks manually by using the **Edit** function. For every alignment cross enter the coordinates and when finished click **Apply**.
NOTE: Whenever possible, your first alignment position should always be on the bottom half (-Y) of the substrate or at 0,0. This will to allow the **Overview** camera to be used if needed.
10. The stage location will initially be at 0,0 (detected substrate center) regardless of the location of your first alignment mark. Click **Move To First Cross** to move to **Pos 1** (Position 1) and begin the alignment process.
NOTE: The current location of the stage is displayed in the **Hardware Info** panel in the upper right corner of the screen.
11. The default camera will be what you selected when you created the **Alignment Settings** template file (either High or Low Res). You should see your first alignment mark in the camera window on the other screen, it may or may not be centered in the display. If you do not see it, you can select a different camera (**Overview** in this case) from the **Stage and Camera Control** frame:

Top Surface

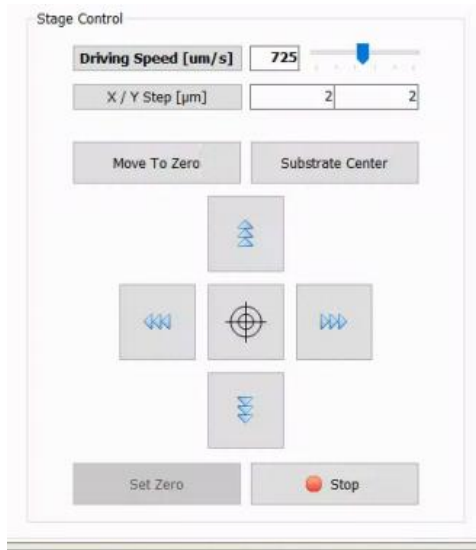


| | Field of view |
|------------------|---------------------------------------|
| High Res | 190 μm x 140 μm |
| Low Res | 640 μm x 480 μm |
| Overview* | 12 mm x 9 mm |

*Overview cannot access the entire surface of the substrate due to mechanical limits.

- Note:** Use the **High Res** or **Low Res** camera for alignment. The **Overview** camera is useful for the initial location of alignment marks or alignment procedures with coarse structures.
12. Now use the controls in the **Stage Control** frame to drive the stage, roughly placing the center of your alignment mark on the crosshair in the middle of the camera window. You want to work your way up to the **High Res** camera as this will provide the most accurate alignment (given your alignment marks are not too big).

MLA150 Operation



- Refer to the stage movement description the previous section for detailed instructions.
13. In the Cross Measurement frame, use the **Alignment Mode** dropdown list to choose between **CrossAlignment** and **ManualAlignment**. This selection can be made for every single position.
- Choose **CrossAlignment** Mode for automatic alignment using digital image recognition.
 - Click **Measure**. The system measures the position of the cross and moves it to the center of the camera window. Optionally Click **Re-Measure** to realign, possibly improving alignment accuracy.
 - Examine the position and click **Accept Position** to confirm it. The procedure moves on to the next alignment cross. In the **Pos** field, the rectangle turns into a green check.

NOTE: Unsatisfying measurements can be repeated by clicking **Re-Measure**. For the finding cross function to work properly it is important that the alignment cross fills the entire camera window. If this was not the case, click **ResizeDetectionArea**. Inside the camera window, a rectangle appears showing the new detection area. To enlarge the detection area, click the right bottom corner of the rectangle without releasing it and drag it to the desired size while holding down the mouse button. To enlarge the detection area again, click **MaximizeDetectionArea** in the panel.

ManualAlignment Mode:

- In this mode, the user locates the alignment mark center by moving the stage.
- Click **Measure**. In the camera window, a crosshair appears. Move the crosshair to the center of your alignment mark*. Once you are satisfied with the placement of the crosshair, click the left mouse button to fix the position. To center the position of the alignment mark inside the camera window, click **Center Cross**. Examine the position and click **Accept Position** to confirm or **Re-Measure** to adjust the position. Once you **Accept Position**, the procedure moves on to the next alignment cross. In the **Pos** field, the rectangle turns into a green check.

***NOTE:** Press S (square) and/or C (circle) on the keyboard and a rectangular and/or a circular frame will appear to support positioning into the center of the mark (both can be on at the same time). The frame can be enlarged or reduced by

using the mouse wheel. Pressing C or S again makes the rectangle/circle disappear. To speed up the resizing of the frame, use Ctrl+ mouse wheel.

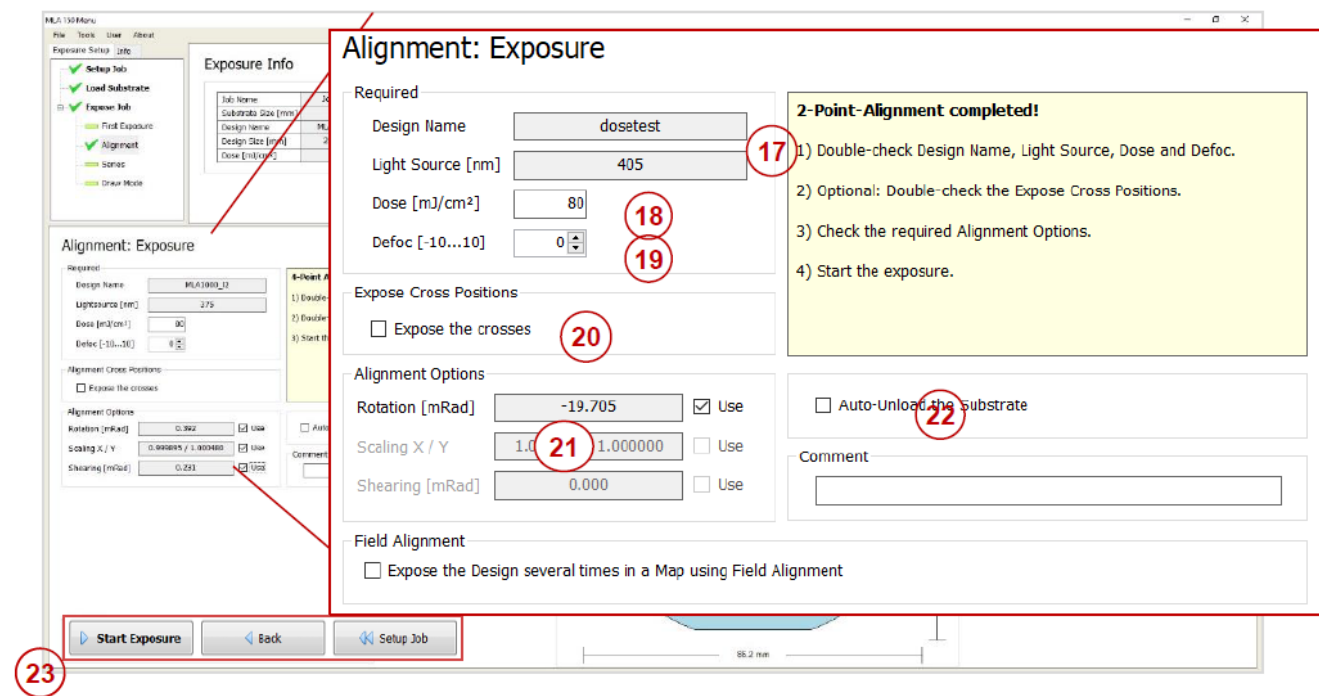
You can skip bad alignment positions by clicking **Skip Position**. Alignment only works if more than two points are available otherwise the button is disabled. In the **Pos** field the rectangle turns red indicating that this coordinate pair was ignored.

14. Repeat the Steps 12 – 14 for all alignment positions.

NOTE: Restarting the alignment procedure is possible by clicking **Restart**. Alternatively, you can click **Setup Job**; the alignment procedure gets cancelled and the Exposure Wizard moves back to the **Setup Job** panel.

15. Once you accept or skip the last alignment position, the **Alignment: Exposure** panel will appear.

In the **Alignment: Exposure** panel:



16. Double-check the **Design Name** and the **Light Source**.

17. Double-check or edit the **Dose** value by entering it into the text field.

18. Double-check or edit the **Defoc** value with the spin buttons (range -25 to 25).

19. If you loaded an **Expose Bitmaps** file in the **Setup Job** panel, verify **Expose the Bitmaps** checkbox is selected and that the settings are correct. You can also view the graphic in the **Substrate** frame which shows the approximate location of the bitmaps as numbered crosshairs.

20. Verify or select the **Alignment Options** (these may have been set at Step 6.e.):

- **Rotation [mRad]:** This checkbox should be activated. The system corrects for the rotation of the substrate by adjusting the CAD file (only if the design has not been converted yet).

MLA150 Operation

- **Scaling X/Y:** The system compares the distance measured during alignment with the distance given by the alignment positions. From the deviation, a scaling factor results. On this basis, the alignment design is shrunk or stretched in order to match the previous layer.
- **Shearing [mRad]:** The system compensates small distortions such as a rectangle that appears more like a parallelogram.

21. If desired, activate **Auto-Unload**. The system executes the unloading procedure automatically.

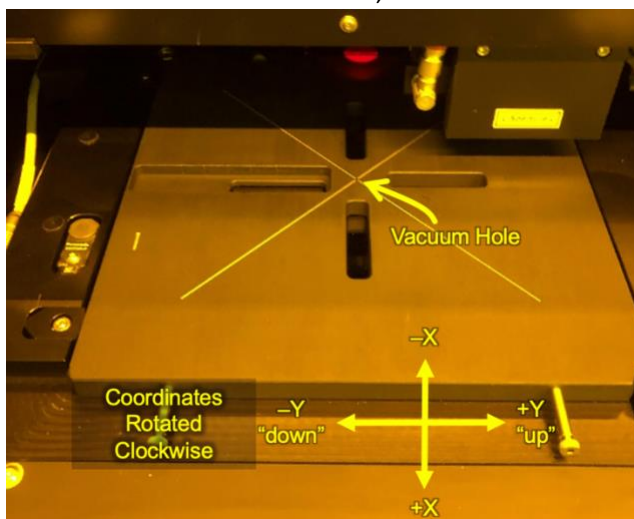
22. Click **Start Exposure**.

Substrate Loading

- The coordinate system is rotated 90° Clockwise, so the Left of the chuck is “down” (-Y), and Right is “up” (+Y).
 - Make sure a flat / straight edge is on the *LEFT* (-Y), for the system to detect substrate rotation.
 - Do not open the Chamber Window during loading/unloading – system will abort stage movements.
1. Load a Substrate Template, if not already done:
In the **Substrate** frame:
 1. Double-click **Substrate Template**.
 2. For whole wafers select **_Automatic round_OAF**
For pieces > 9mm select **_Automatic rectangular_Std_OAF**
For pieces < 9mm select **_Automatic rectangular_Sml_OAF**
Then click **Load**.
 2. Fill in the Job Name, Exposure Mode, Laser and Design as detailed above.
 3. Verify the stage is in the load/unload position (see photo below).

If stage is not in load/unload position, then:

- a. Close the Chamber Window and click on **Unload Substrate** in the **Setup Job** panel.
A pop-up will appear confirming you want to unload, click **OK**.
Once the unload process is complete another window will pop-up stating the substrate has been unloaded, click **OK**.



Stage in Load/Unload Position

4. Click the **[Substrate Load]** Button and follow the instructions.
5. If needed, turn on the flow/environmental box light by pressing the orange button on the front of the system.
6. Press the lower red button (↑↓) to open the sash of the flow box.

MLA150 Operation

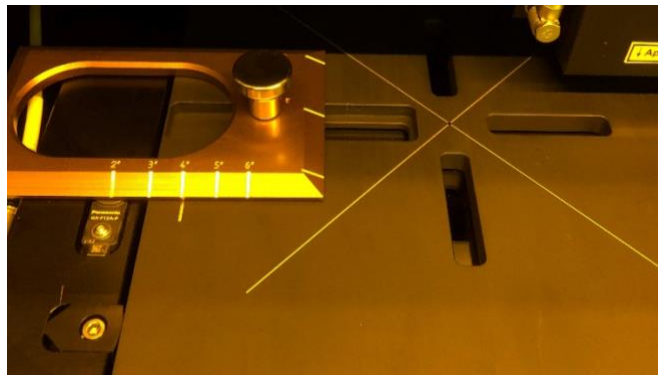
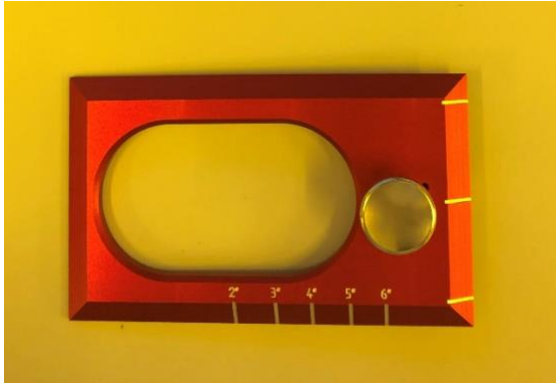


← Lighting

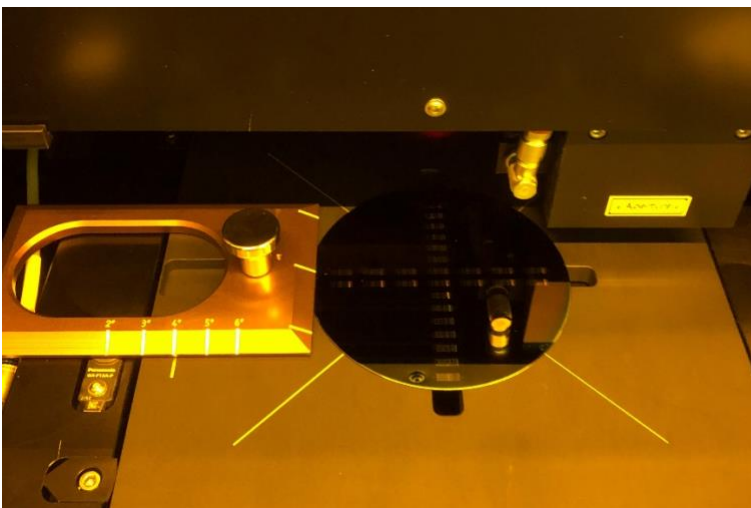
← Open/Close Window

If Loading a Full Wafer (round)

7. Find the wafer flat alignment fixture from inside the flow box and place it on the chuck as shown. There are labeled increments on the fixture for 2 – 6” wafers. Line up the increment corresponding to your wafer size with the white hash mark on the stage, you will feel an indent for each increment.



8. Place your wafer on the chuck and press the Wafer Flat to the Left, against the alignment fixture as shown.

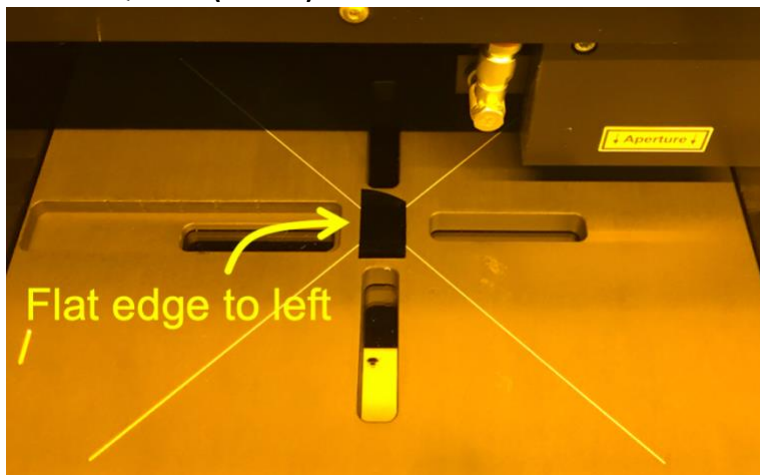


MLA150 Operation

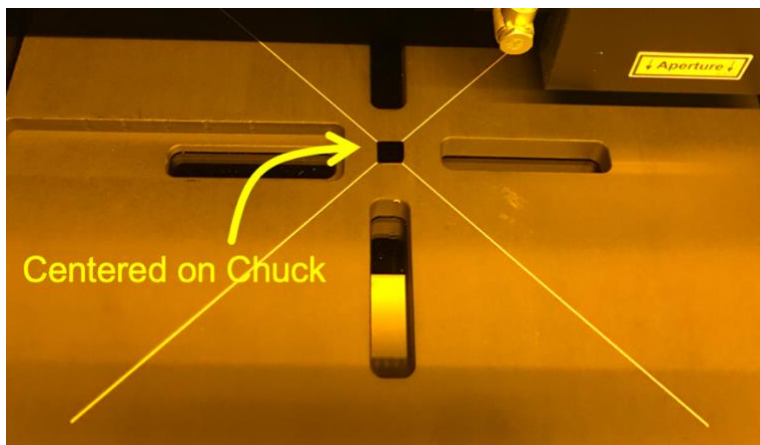
If Loading a Piece (irregular or rectangular)

9. Make sure to place the piece centered on the chuck. Important to prevent crashing and for good vacuum.
 - a. Try to position the piece as straight as possible, with a flat-edge to the left for automatic substrate rotation measurement.

Cleaved Quarter (> 9mm):



≤ 9mm Piece:



10. Turn On Vacuum: To your right, inside the flow box, is the chuck vacuum control. Press the button below the display to turn on the vacuum. You will hear a leaking air sound, which is normal since the vacuum is created using a Venturi. The upper reading on the Vacuum display should be better than -0.49 bar. If it is not, turn off the vacuum and inspect the back of your substrate for cleanliness.

MLA150 Operation



11. Push the sample from the side to ensure sample is held well by vacuum.
12. **IMPORTANT:** Remove the alignment fixture from the chuck and close the sash.
 - a. **Make sure nothing on the stage is taller than the sample, and sample is centered, to prevent crashing the exposure optics!**
13. Press [**Continue**], the system will drive the wafer stage under the exposure lens.
14. The system will pause again, while you **visually verify the sample is under the lens.**
15. If you chose the small (< 9mm) substrate template ***Automatic rectangular_Sml_OAF:***
 - a. The system will ask you to locate the substrate center manually, using the Overview camera. Click the crosshair in the center of your substrate before continuing. You can use the C/S keyboard keys and Mouse-Wheel up/down to aid in aligning the substrate.
16. Press [**Continue**] if you are sure the sample is under the lens. If unsure, [**Cancel**] and check that the substrate is in the stage center.
 - a. The system will bring the exposure lens down on the sample, and measure the sample edges using the pneumatic focus detection.
17. You may encounter a **Find Plate Center** pop-up window indicating that the measured size of the substrate differs from the programmed size.
 - a. Verify the measured size & shape is correct for your sample, and select **Yes**.
 - b. If the wrong substrate template was chosen (eg. round instead of rectangular) click **No** and go back to [**Setup**] to make the correction.

Important: If the the exposure lens engages off the edge of the sample, or sample is too small, the exposure lens will crash sideways into the sample and/or photoresist on the next step. Contaminating the exposure lens' pneumatic autofocus may affect lithography defocus on all user's exposures.

Substrate Unload

To unload the substrate:

1. go back to the Setup screen by clicking [**<< Setup**], and
2. choose [**Unload Substrate**]

MLA150 Operation

3. Turn off the Vacuum, and remove your sample.

Re-align the Substrate Rotation

If flat/edge alignment is critical, or when exposing a layer with Alignment, it is recommended that the measured substrate angle reading “**Global Angle**” be $< 10 \text{ mRad}$ ($< 0.6^\circ$). This measurement is found on the **First Exposure** and **Alignment** screens.

If the measured substrate angle is $>10 \text{ mRad}$ and you want to realign rotation manually:

18. Click [**<< Setup Job**] at the bottom of the screen to return to the **Setup Job** panel.
19. Click **Unload Substrate**, a pop-up window will appear confirming you want to unload, click **OK**.
20. Wait for the unload sequence to complete. A pop-up window will appear indicating the substrate has been unloaded, click **OK**.
21. Open the sash,
22. release the chuck vacuum, and
23. reposition your substrate using the corresponding alignment fixture.
24. Engage the chuck vacuum,
25. remove the alignment fixture, and
26. close the sash.
27. Return to **Substrate Loading**.

Design Conversion

The XWindows Conversion software is case-sensitive, and files must be placed in the exact directory expected for the software to function properly.

Your design files must be located in the appropriate file-type folder, one of:

- C:\HIMT\Designs\gdsii
- C:\HIMT\Designs\bmp
- C:\HIMT\Designs\dxg
- C:\HIMT\Designs\cif
- C:\HIMT\Designs\gerber

Subfolders within these are *not* supported.

Filenames must not have any spaces, but underscores `_` are allowed.

File extensions (`.gds`, `.cif`) must be lowercase or XWindows will not show them in the file browser. (KLayout.app saves as capital `".GDS"` by default.)

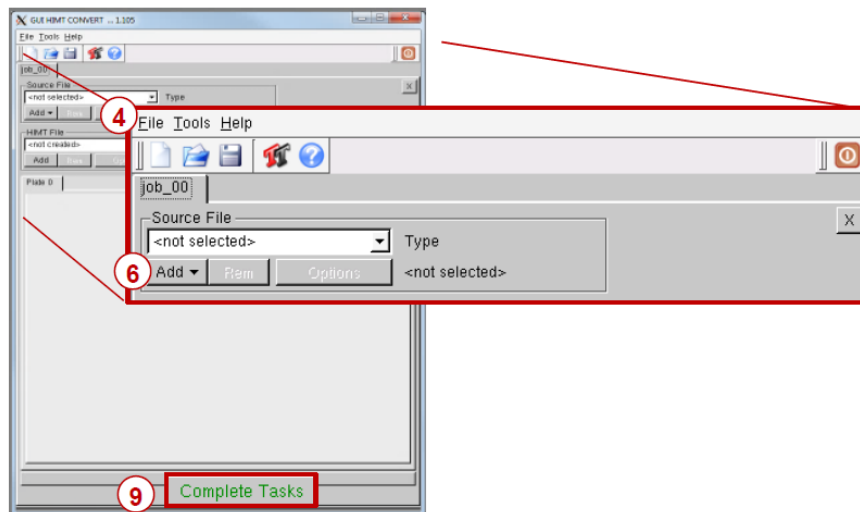
In the **Layer** frame:

1. Double-click into the value field titled **Design**. The **Load Design** panel containing a list of designs opens, where you normally select one of them for your exposure.
2. To create a new design, click **Convert Design**.



3. The conversion software opens.

In the **Conversion** window:




4. From the menu bar, select **File**→**New Job**.
5. Enter a name for the job using the naming convention and click **Ok**.

MLA150 Operation

- The naming convention is *LastnameFirstinitial_jobname* or *companyname_jobname* (e.g. *sawyerl_myfirstjob* or *staff_trainingjob_oct10*).
6. Click the **Add** drop down menu and select a design format. A pop-up window will appear that shows the directory containing the source files for the selected design format.
 7. From the directory, select the file to be converted.
 8. A pop-up window will appear giving you various options depending on the file format:

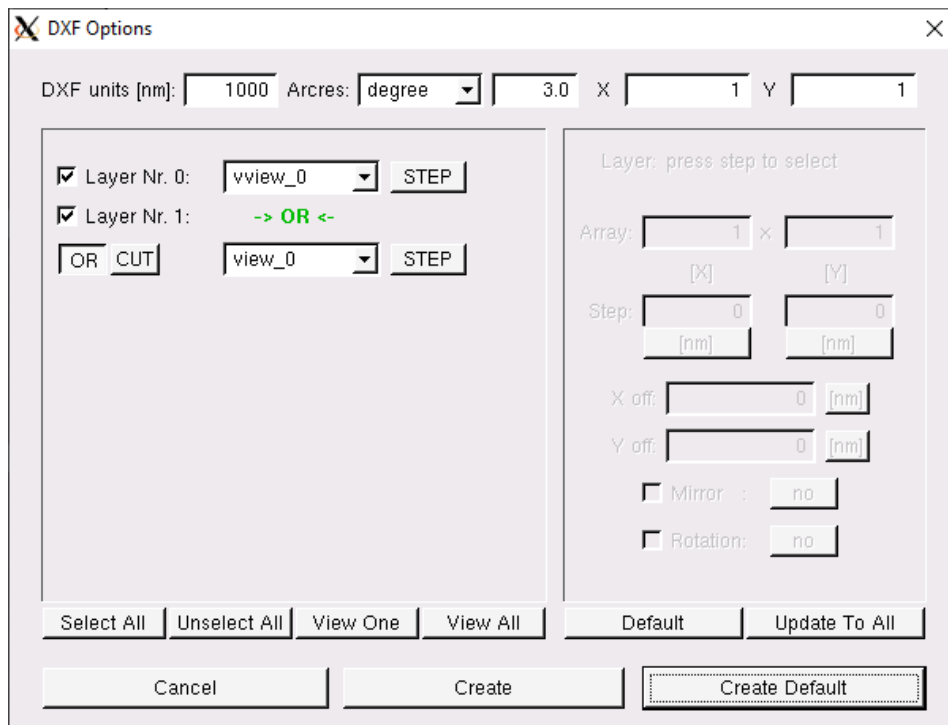
CIF



The CIF Options dialog box contains the following fields and buttons:

- Top Cell:
- Scale X:
- Scale Y:
- Layer:
- Buttons: Cancel, Create, Create Default

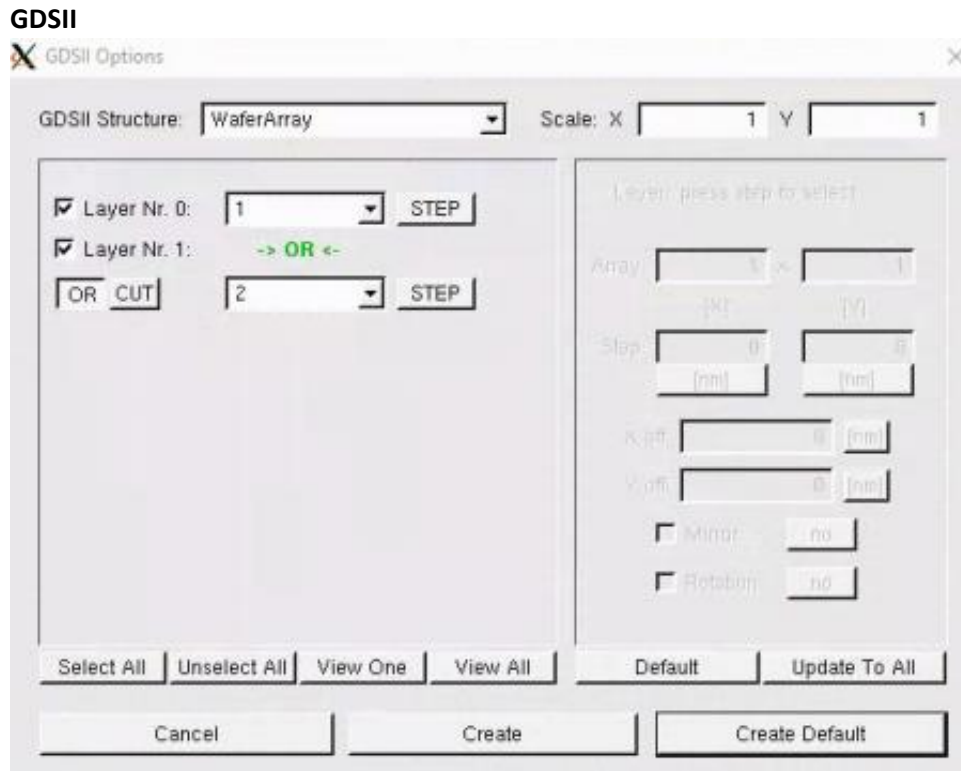
DXF



The DXF Options dialog box contains the following fields and buttons:

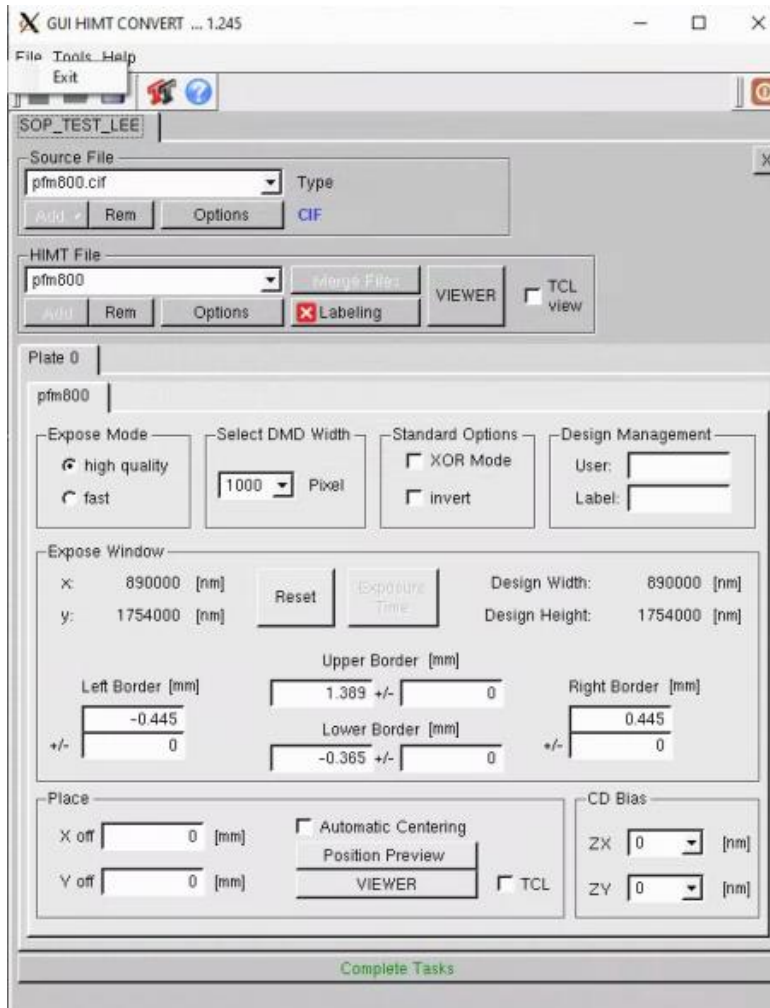
- DXF units [nm]:
- Arcres:
- 3.0 X Y
- Layer Nr. 0:
- Layer Nr. 1: (with **-> OR <-** between them)
- Buttons: OR, CUT, Select All, Unselect All, View One, View All, Default, Update To All, Cancel, Create, Create Default
- Additional options on the right: Layer: press step to select, Array: x (with [X] and [Y] labels), Step: [nm] (for X and Y), X off: [nm], Y off: [nm], Mirror: , Rotation:

MLA150 Operation



- Note that the “→ OR ←” option will combine/ Boolean Union the selected layers.
9. Once you have all of your settings correct, click **Create Default**.
 10. The **Conversion** window will populate with more settings that pertain to the quality of the write and the placement of the design.

MLA150 Operation



11. Before making any changes you should verify that your settings are correct from the file option window:
 - Check your **Design Width & Height** in the **Expose Window** frame, you can change the unit of measure by clicking on it.
 - You can view a preview of your design by clicking on the **VIEWER** button in the **HIMT File** frame. The viewer will also allow you to measure feature sizes.
 - Check the placement of your design using the **Border** data provided in the **Expose Window** frame.
 - **Untested: Increasing the border values may aid in stitching together of inverted exposes that don't have the correct data extent markers.**
12. The standard write quality settings are automatically populated, **high quality & 1000 Pixel DMD width**, and are recommended as a starting point for new users. Other commonly used settings/options:
 - **XOR Mode** – overlapping objects will subtract each other.
 - **invert** – changes the polarity of your design (dark field design would write as clear field). The data extents are important for this option.
 - **Automatic Centering** – Centers your design – warning, this will adjust your design's (0,0) origin.

MLA150 Operation

13. Click **Complete Tasks**, a save file pop-up window will appear with the file name you designated in Step 5, there is no need to change the name so just click **Save**.
14. A file conversion window will appear, once the **Status** reads **Done!** And the status bar is at 100%, click **Finish**.
15. Your new design file file will appear highlighted in the MLAMenu file list. Either select **Load** or double click the file to add it to the job.